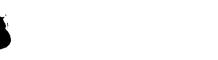
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A3

PA



1. (Amended) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;
heating the applied fluxing agent to deoxidize the surface of the aluminum body
part;

applying a tin- based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin- based solder filler consists of, by weight, of 81% to 85% Sn, 3% to 5% Zn, and 12% to 14% Cu; and

heating the solder filler to bond the solder filler to the aluminum body part.

(Amended) The method of claim 21 wherein the solder filler consists of, by weight, 66.5% Sn, 30% Zn, and 3.5% Ni.

(Amended) The method of claim 22 wherein the solder filler consists of, by weight, of 80% Zn and 20% Al.

5 1. (Amended) A method of applying a solder filler to an aluminum body part comprising the steps of:

forming a filler/flux mixture comprising a tin-based solder filler for aluminum body parts and a fluxing agent wherein the melting point temperature of the solder filler is at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 81% to 85% Sn, 3% to 5% Zn, and 12% to 14% Cu;

applying the filler/flux mixture to the aluminum body part; and heating the filler/flux mixture to bond the solder filler to the aluminum body part.

is comprised of by weight about 10% of the fluxing agent and about 90% of the tin-based solder filler.

Please add claims 21-23 as follows:

PX

(New) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part; heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a tim-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 55% to 85% Sn, 12% to 40% Zn, and 3% to 5% Ni, Fe, Cu or Co; and

heating the solder filler to bond the solder filler to the aluminum body part.

(New) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;

heating the applied fluxing agent to deoxidize the surface of the aluminum body
part;

applying a zinc-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the zinc-based solder filler consists of, by weight, of 78% to 89% Zn and 11% to 22% Al; and

heating the solder filler to bond the solder filler to the aluminum body part.

(New) The method of claim 1 wherein the forming step is comprised of providing the tin-based solder filler in the form of a hollow wire and injecting the fluxing agent into the hollow wire.

